

WHAT IS CLAIMED IS:

1. A method of chemical mechanical polishing (CMP) a first material on a second material of a semiconductor die, said method comprising:
  - defining a plurality of substantially identical semiconductor dies on a semiconductor wafer, said wafer having a planar surface, and wherein said plurality of dies are separated from one another by a scribe line;
  - 5 forming a layer of said second material on said planar surface wherein said layer of said second material having a top surface, substantially parallel to said planar surface;
  - forming a layer of said first material on said top surface, wherein said layer of said first material varying in a height direction above said top surface;
  - 10 forming a mask across the wafer, wherein said mask having a plurality of locations with each location having differing density of gap to pillar ratio, which is proportional to the height of said first material above said top surface;
  - anisotropically etching said first material through each gap of said mask, across the wafer, wherein each gap is etched by the same amount in the height direction; and
  - 15 using CMP to planarize said first material to said top surface across the wafer.
2. The method of claim 1 wherein said layer of second material is silicon nitride, and wherein said layer of first material is silicon dioxide.
3. The method of claim 1 further comprising a layer of third material between said layer of second material and said wafer.
- 20 4. The method of claim 3 wherein said layer of second material is silicon nitride, and wherein said layer of first material and third material are silicon dioxide.

5. The method of claim 4 wherein said layer of second material has holes therein connecting said layer of first material and third material.
6. The method of claim 5 wherein each of said dies has trenches therein filled with said layer of first material.
- 5 7. The method of claim 6 wherein said density of gap to pillar comprises a plurality of substantially congruent fields with each field having the same size pillar but different size gap.
8. The method of claim 6 wherein said density of gap to pillar comprises a plurality of substantially congruent fields with each field having different size pillar but same size gap.
9. The method of claim 1 wherein said density of gap to pillar comprises a plurality of 10 substantially congruent fields with each field having the same size pillar but different size gap.
10. The method of claim 1 wherein said density of gap to pillar comprises a plurality of substantially congruent fields with each field having different size pillar but same size gap.
11. A method of planarizing a first material on a second material of a semiconductor die, said method comprising:
  - 15 defining a plurality of substantially identical semiconductor dies on a semiconductor wafer, said wafer having a planar surface, and wherein said plurality of dies are separated from one another by a scribe line;
  - forming a layer of a third material on said planar surface;
  - forming a layer of said second material on said layer of third material, said layer of said 20 second material having a top surface substantially parallel to said planar surface;
  - masking selective portions of said layer of second material, with other portions of said layer of second material unmasked;

etching said layer of second material, said layer of first material, and said semiconductor wafer to form trenches therein, through said other portions unmasked;

applying said layer of said first material on said wafer, including in said trenches and on said second material, wherein said layer of said first material varying in a height direction above 5 said top surface;

forming a mask across the wafer, wherein said mask having a plurality of locations with each location having differing density of gap to pillar ratio which is proportional to the amount of said first material in the height direction from said top surface at said location;

anisotropically etching said first material through each gap of said mask, across the wafer, 10 wherein each gap is etched by the same amount in the height direction; and using CMP to planarize said first material to said top surface across the wafer.

12. The method of claim 11, wherein said masking step further comprises:

forming a mask covering select portions of said layer of second material with other portions unmasked; and

15 removing said mask after said etching step.

13. The method of claim 12 wherein said first material and said third material is silicon dioxide, and said second material is silicon nitride.

14. The method of claim 12 wherein said density of gap to pillar comprises a plurality of substantially congruent fields with each field having the same size pillar but different size gap.

20 15. The method of claim 12 wherein said density of gap to pillar comprises a plurality of substantially congruent fields with each field having different size pillar but same size gap.